RL78/G14, H8/36109

Migration Guide from H8 to RL78: CPU architecture

Introduction

This application note describes how to migrate the CPU architecture of the H8/36109 to the CPU architecture of the RL78/G14.

Target Device

RL78/G14, H8/36109

When using this application note with other Renesas MCUs, careful evaluation is recommended after making modifications to comply with the alternate MCU.

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1. Differences in Function Overview

Table 1.1 overviews the differences between the CPU architecture of the H8/36109 and those of the RL78/G14.

Table 1.1 Differences

Item	H8/36109	RL78/G14
General register	16 16-bit registers (Also usable as 8-bit registers or 32-bit registers)	4 banks of 8 8-bit registers (Also usable as 16-bit registers)
Basic instructions	62 instructions	81 instructions (Note)
Address space	16M bytes	1M bytes
Program counter	24-bit	20-bit
Condition-Code register	CCR Register	PSW Register

Note. RL78-S3 core only

Figure 1.1 shows the configuration of general-purpose registers of the H8/36109.

Figure 1.1 Configuration of H8/36109 general-purpose registers

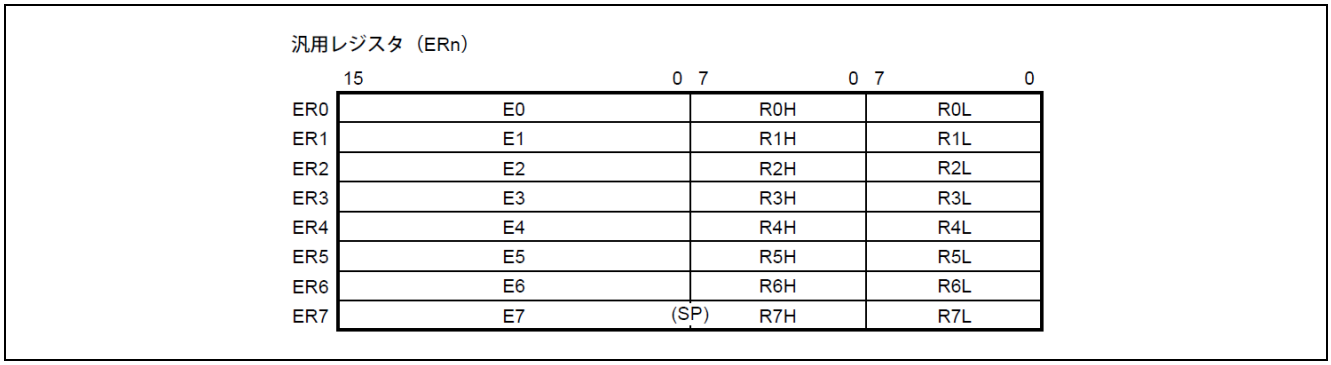


Figure 1.2 shows the configuration of general-purpose registers of the RL78/G14.

Figure 1.2 Configuration of RL78/G14 general-purpose registers

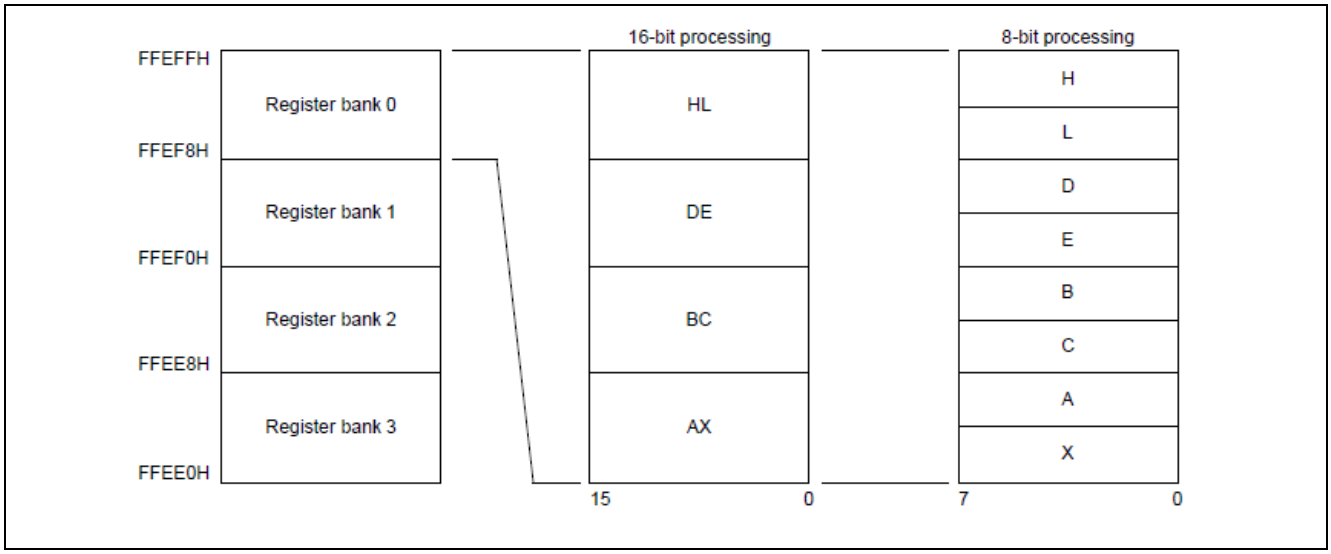
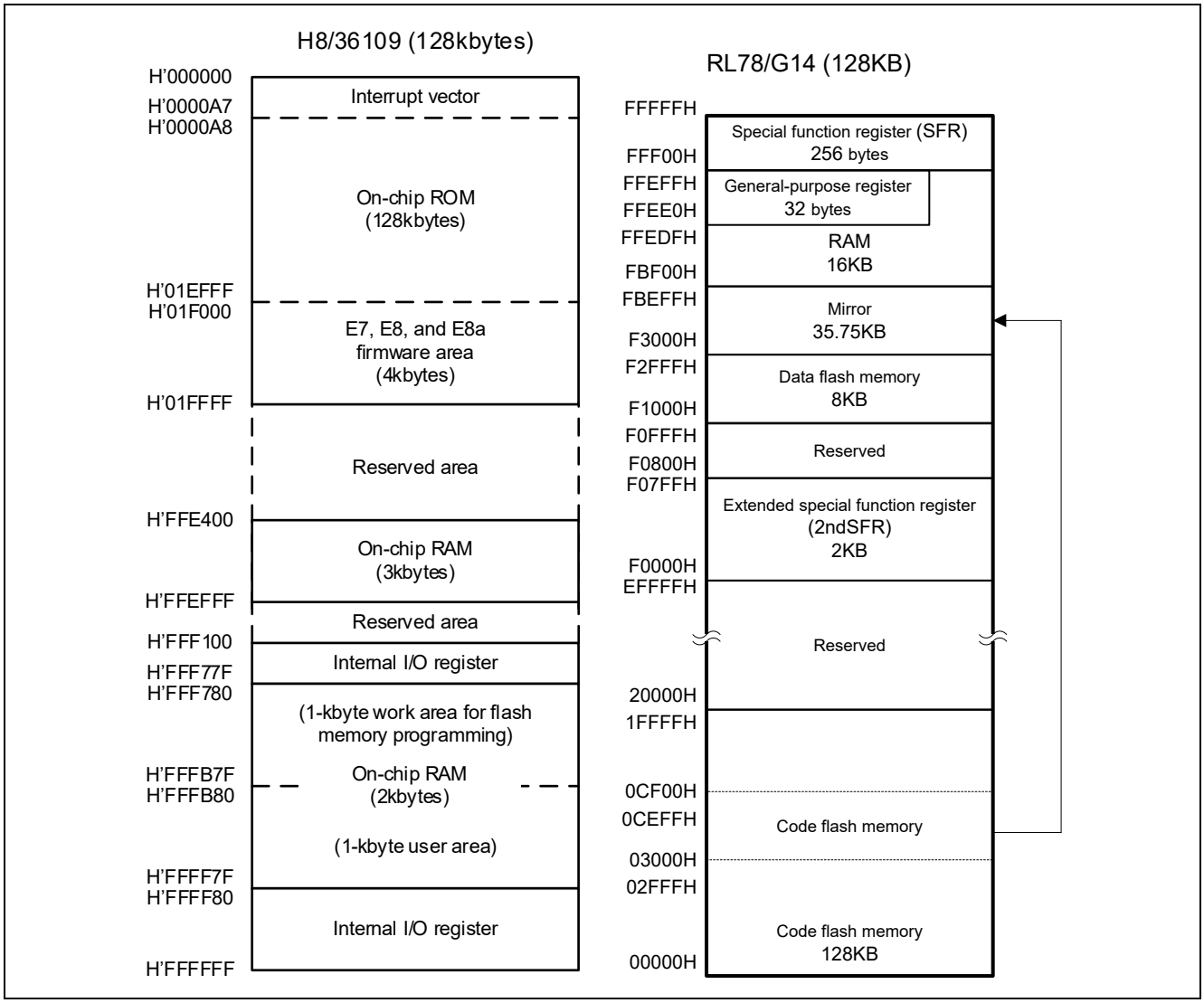


Figure 1.3 shows the memory maps of the 128Kbyte flash memory for the H8/36109 and the RL78/G14.

Figure 1.3 Memory maps of 128Kbyte flash memory for the H8/36109 and the RL78/G14



H8/36109 have an H8/300H CPU with an internal 32-bit architecture that is upward-compatible with the H8/300 CPU, and supports only advanced mode, which has a 16-Mbyte address space.

RL78/G14 can access a 1 MB address space. RL78/G14 can access 1Mbyte memory space (00000H - FFFFFH) by using the ES and CS registers. In addition, RL78/G14 has a mirror area containing the same content as the code flash memory, allowing the CPU to read the content of the code flash memory with short code.

2. Reference Documents

User's Manual:

- RL78/G14 User's Manual: Hardware (R01UH0186)
- RL78 family User's Manual: Software (R01US0015)
- H8/36109 Group User's Manual: Hardware (R01UH0294)
- H8/300H Series Software Manual (REJ09B0213)

The latest versions can be downloaded from the Renesas Electronics website.

Technical Update/Technical News:

The latest information can be downloaded from the Renesas Electronics website.

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Jun.08, 2020	-	First edition issued

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

   A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.
2. Processing at power-on

   The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.
3. Input of signal during power-off state

   Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.
4. Handling of unused pins

   Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.
5. Clock signals

   After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.
6. Voltage application waveform at input pin

   Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).
7. Prohibition of access to reserved addresses

   Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.
8. Differences between products

   Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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